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Full Material Declaration for attached parts list

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Diotec Semiconductor

Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2014 [Approved on 16 February 2024, 13:12 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.2%	Nickel REACH Article 67 Exemption	7440-02-0	1%
			Gold	7440-57-5	11.5%
			Polydimethylsiloxane rubber	63394-02-5	25%
			Silicon	7440-21-3	62.5%
Die attach	Lead and Lead alloys	1.3%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	15%	Carbon black	1333-86-4	0.3%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	0.8%
			Tetrabromobisphenol A (TBBPA) Exempt from other regulatory requirements	79-94-7	0.99%
			resin epoxy	61788-97-4	27.61%
			Quartz sand	60676-86-0	70.3%
Leadfinish	Tin plating	9%	Copper	7440-50-8	0.8%
			Silver	7440-22-4	3.7%
			Tin	7440-31-5	95.5%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Leadframe	Copper (e.g. copper amounts in cable harnesses)	74.5%	Nickel REACH Article 67 Exemption	7440-02-0	0.4%
			Copper	7440-50-8	99.6%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-213AA/Plastic (Minimelf:~SOD80)	Diode SMD	0.04	g